LISTING OF CLAIMS:

Claims 1-11 were cancelled by a prior amendment. Claims 12-24 are currently amended. New claims 25 -27 have been added. No new matter has been added to the claims.

The following listing of claims will replace all prior versions of claims in the present application.

Claims 1-11 (Canceled)

12. (Currently amended) A laser ~~Laser~~ machining device for drilling holes in fluid injection device components, particularly for injecting fuel into a combustion engine, said machining device comprising a laser resonator formed of a first solid state active medium and first optical pumping means, said first optical pumping means being formed by laser diodes, wherein:

- ~~Said~~ said resonator ~~is arranged for generating~~ generates primary pulses having a length within or greater than the microsecond range; and
- the machining device ~~further~~ includes modulation means arranged between said resonator and a machining head, said modulation means being controlled ~~to supply a~~such that a secondary pulse train is ~~at~~ output for each primary pulse entering therein.

13. (Currently amended) The laser machining device ~~Device~~ according to claim 12, ~~wherein it includes~~ further comprising an optical diode arranged downstream of said resonator.

14. (Currently amended) The laser machining device ~~Device~~ according to claim 12, ~~wherein it~~ further ~~includes~~ comprising means for amplifying the pulses supplied by said resonator.

15. (Currently amended) ~~Device~~ The laser machining device according to claim 13, ~~wherein it~~ further ~~includes~~ comprising means for amplifying the laser pulses supplied by said resonator, said amplification means being arranged downstream of said optical diode.

16. (Currently amended) ~~Device~~ The laser machining device according to claim 13, wherein said optical diode is formed by a linear polarizer and by a quarter-wave plate arranged following said polarizer.

17. (Currently amended) ~~Device~~ The laser machining device according to claim 15, wherein said optical diode is formed by a linear polarizer and by a quarter-wave plate arranged following said polarizer.

18. (Currently amended) ~~Device~~ The laser machining device according to claim 14, wherein said amplification means are controlled ~~so as to provide~~such that amplification pulses are provided with a time lag relative to the primary pulses ~~in order to~~ such that ~~modulate~~ the amplitude of said secondary pulses is modulated.

19. (Currently amended) ~~Device~~ The laser machining device according to claim 15, wherein said amplification means are controlled ~~so as to provide~~such that amplification pulses are provided with a time lag relative to the primary pulses ~~in order to~~such that ~~modulate~~ the amplitude of said secondary pulses is modulated.

20. (Currently amended) ~~Device~~ The laser machining device according to claim 14, wherein said amplification means include a cavity formed by a second solid state active medium and by second optical pumping means formed by a flash lamp.

21. (Currently amended) ~~Device~~ The laser machining device according to claim 18, wherein said amplification means include several active mediums defining several amplification levels, each of said active mediums being pumped by a flash lamp.

22. (Currently amended) ~~Device~~ The laser machining device according to claim 12, wherein said resonator is arranged for supplying at the outlet thereof a linearly polarized laser beam.

23. (Currently amended) ~~Device~~ The laser machining device according to claim 21, wherein said first active medium is formed by a crystal selected from among crystals that directly generate a linearly polarized light, in particular a Nd:YVO_4 crystal.

24. (Currently amended) ~~Device~~ The laser machining device according to claim 12, wherein ~~it is arranged for~~ said resonator supplies primary ~~supplying~~ pulses in the microsecond range ~~whose~~ having an energy such that ~~energy enables~~ a hole ~~to~~ may be drilled in a given component by a single primary pulse generated by said resonator.

25. (New) The laser machining device according to claim 12, wherein each of the primary pulses has a length between fifty microseconds (50 μs) and one millisecond (1 ms).

26. (New) The laser machining device according to claim 12, wherein each of the secondary pulses as a length between one microsecond (1 μs) and twenty microseconds (20 μs).

27. (New) The laser machining device according to claim 25, wherein each of the secondary pulses as a length between one microsecond (1 μs) and twenty microseconds (20 μs).